

Application No.: 09/849,457

Docket No.: JCLA6623-R

**AMENDMENTS****In The Claims:****Claims 1-13. (canceled).**

Claim 14. (currently amended) A method for forming a light emitting device, the method comprising:

providing a covering layer;

providing a light emitting unit, comprising a metal cathode layer;

forming a recess region on a covering surface of the covering layer;

performing an evaporation depositing process, to form an active gas-moisture absorption layer ~~[[on-]]~~ directly in contact with a bottom of the recess region of the covering surface of the covering layer; and

putting the covering layer with the covering surface having the active gas-moisture absorption layer over at least a portion of the light emitting unit above the metal cathode layer.

Claim 15. (original) The method of claim 14, wherein the metal cathode layer comprises one selected from the group consisting of Li, Mg, and Ca.

Claim 16. (previously presented) The method of claim 14, wherein the active gas-moisture absorption layer comprises one selected from the group consisting of Li, Mg, and Ca.

**Claim 17-20. (cancelled)**

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Claim 21. (previously presented) The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer and the metal cathode layer are sequentially formed on the substrate; and

forming a sealant layer, at least covering the light emitting layer and the metal cathode layer;

wherein the covering layer is put, by the covering surface over at least a portion of the sealant layer above the metal cathode layer.

**Claim 22. (cancelled)**

Claim 23. (previously presented) The method of claim 21, wherein in the step of providing the covering layer, the covering layer comprises a cap-like layer to completely cover over the sealant layer, the transparent anode layer, light emitting layer, and the metal cathode layer.

Claim 24. (previously presented) The method of claim 14, wherein in the step of performing the evaporation depositing process, the active gas-moisture absorption layer is formed on a recessed surface of the recess region.

Claim 25. (previously presented) The method of claim 23, wherein further comprises a clearance between the cap-like covering layer and the sealant layer.

Claim 26. (previously presented) The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer,

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the metal cathode layer and another active gas-moisture absorption layer at least covering the metal cathode layer are sequentially formed on the substrate; and

forming a sealant layer, at least covering the light emitting layer and the metal cathode layer;

wherein the covering layer is put, by the covering surface over at least a portion of the sealant layer above the metal cathode layer.

Claim 27. (currently amended) The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer and the metal cathode layer are sequentially formed on the substrate;

forming a sealant layer, at least covering the metal cathode layer;

etching the covering layer to form ~~[[a]]the~~ recess region on the covering layer at a covering surface with respect to the metal cathode layer, and forming a trench enclosing the recess region;

wherein in the step of performing an evaporation deposition process, the active gas-moisture absorption layer is formed on the covering layer within the recess region;

coating a gluing layer on a portion of the covering layer between the trench and the recess region; and

adhering the covering layer onto the transparent substrate.

Claim 28. (previously presented) The method of claim 27, wherein the step of etching covering layer comprises performing a sand-jet etching process.

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Claim 29. (previously presented) The method of claim 28, wherein the step of etching covering layer comprises performing a sand-jet etching process with etchant of aluminum oxide particles.

Claim 30. (previously presented) The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer and the metal cathode layer are sequentially formed on the substrate;

forming a sealant layer, at least covering the light emitting layer and the metal cathode layer;

forming two frit lines on the covering layer, enclosing the active gas-moisture absorption layer, wherein a clearance between the two frit lines is reserved;

properly dripping a sealant material on the clearance; and

adhering the covering layer on the transparent substrate layer through the sealant material, wherein the active gas-moisture absorption layer is above the metal cathode layer.